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(5-2008)



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Vishay Semiconductors

High Speed Infrared Emitting Diodes, 940 nm, **Surface Emitter Technology**



FEATURES

• Package type: surface-mount

• Package form: 0805

• Dimensions (L x W x H in mm): 2 x 1.25 x 0.8

Peak wavelength: λ_p = 940 nm

· High speed

• Angle of half intensity: $\varphi = \pm 60^{\circ}$

• 0805 standard surface-mountable package

• Floor life: 168 h, MSL 3, according to J-STD-020

· Lead (Pb)-free reflow soldering

 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the SurfLightTM portfolio, the VSMY5940 is an infrared, 940 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, in a low profile 0805 surface-mount (SMD) package.

APPLICATIONS

- · Miniature light barrier
- · Optical switch
- IR point source
- Wearables

PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr) at I_F = 100 mA	φ (°)	$\lambda_{\mathbf{p}}$ (nm)	t _r (ns)
VSMY5940	14.5	± 60	940	5

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMY5940	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805	

Note

· MOQ: minimum order quantity





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ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V_R	5	V	
Forward current		I _F	100	mA	
Peak forward current	$t_p/T = 0.1$, $t_p = 100 \mu s$	I _{FM}	200	mA	
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA	
Power dissipation		P_V	200	mW	
Junction temperature		Tj	125	°C	
Operating temperature range		T _{amb}	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +110	°C	
Soldering temperature	According to Fig. 7, J-STD-020	T _{sd}	260	°C	
Thermal resistance junction to ambient	EIA / JESD51	R _{thJA}	240	K/W	
ESD sensitivity	According to ANSI / ESDA / JEDEC JS-001	V _{ESD}	2	kV	

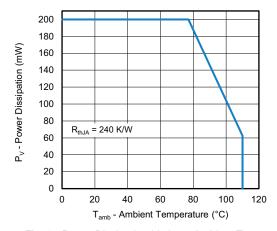


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

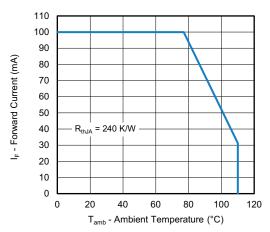


Fig. 2 - Forward Current Limit vs. Ambient Temperature

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	1.4	1.7	2.0	V
Temperature coefficient of V _F	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	TK _{VF}	-	-1.2	-	mV/K
Reverse current		I _R	Not designed for reverse operation			μΑ
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz,}$ $E = 0 \text{ mW/cm}^2$	CJ	-	30	-	pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	10	14.5	19	mW/sr
Temperature coefficient of radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	TKφ _e	-	-0.3	-	%/K
Angle of half intensity		φ	-	± 60	-	0
Peak wavelength	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	λ_{p}	=	940	-	nm
Spectral bandwidth	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	Δλ	=	65	-	nm
Temperature coefficient of λ_p	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	TK_{\lambdap}	-	0.28	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	5	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	5	-	ns

20°

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

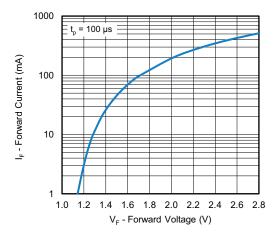
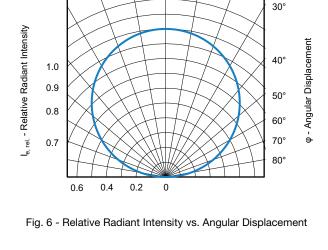


Fig. 3 - Forward Current vs. Forward Voltage



0°

10°

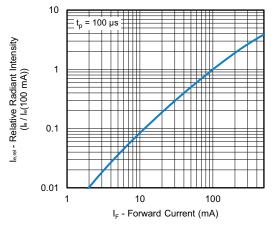


Fig. 4 - Relative Radiant Intensity vs. Forward Current

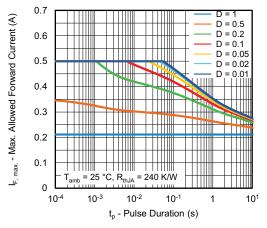


Fig. 7 - Max. Allowed Forward Current vs. Pulse Duration

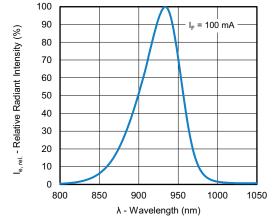


Fig. 5 - Relative Radiant Intensity vs. Wavelength

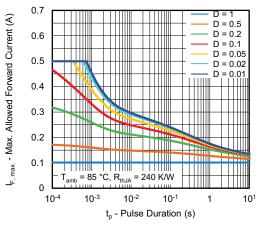


Fig. 8 - Max. Allowed Forward Current vs. Pulse Duration





REFLOW SOLDER PROFILE

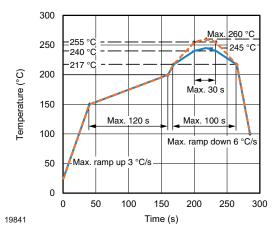


Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

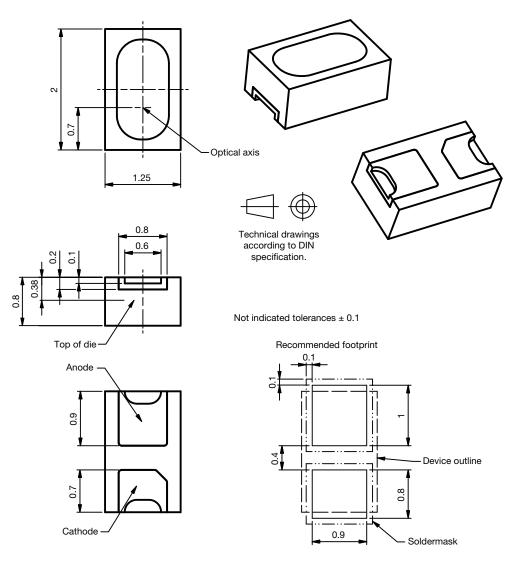
Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



PACKAGE DIMENSIONS in millimeters

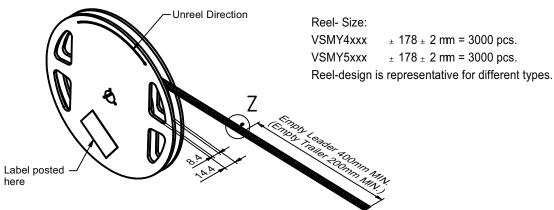


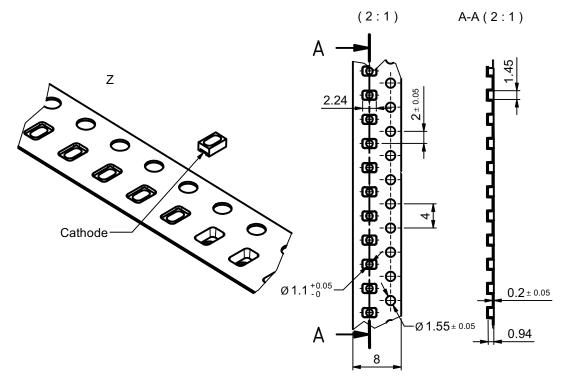
Drawing- No.: 6.550-5352.01-4 Issue: 2_A; prelim. 05.12.2024



TAPE AND REEL DIMENSIONS in millimeters

Non tolerated dimensions ± 0.1 mm





Drawing-No.: PM-10035.100-000 Issue: 0_A; preliminary 10.12.2024



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